

### EIA STANDARD

# VISUAL AND MECHANICAL INSPECTION MULTILAYER CERAMIC CHIP CAPACITORS

**EIA-595-A** 

(Revision of EIA-595)

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Exhibit 1009



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(From Standards Proposal No. 5094 formulated under the cognizance of the P-2.1 Committee on Ceramic Capacitors)

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### **CONTENTS**

		Page
Foreword		iii
Clause		
I	Scope	1
2	Ceramic surface inspection	1
2.1	Cracks	ı
2.2	Chipped areas	I
2.3	Pinholes, holes, and voids in the ceramic body	2
2.4	Delamination	3
2.5	Blisters or foreign material	3
2.6	Warpage and protrusions	4
2.7	Marking	4
3	End metallization inspection	4
3.1	Pinholes and voids	4
3.2	Bandwidth	5
3.3	Stringers and smears	5
3.4	Edge reduction	6
3.5	Lifting or peeling of terminations	6
3.6	Foreign material	7
3.7	Bumps and protrusions	7
4	Pretinned solder termination inspection	7
4.1	Solder coverage	7
4.2	Leaching	8
4.3	Oversize	8
5	Plated nickel/tin or nickel/solder inspection	8
5. I	Barrier thickness	8
5.2	Tin or solder thickness	8
5.3	Plating bloom	9
5.4	Tarnished end metallization	9
		·
Figures		
I	Cracks	ı
2	Chipping (chipouts and chipins)	2
3	Pinholes	2
4	Delamination	3
5	Blisters and foreign material	3
6	Warpage	4
7	Marking	4
8	End metallization voids	5
9	Bandwidth	5
10	Stringers	6
11	Chipped termination edges	6
12	Lifted terminations	6
13	Foreign material	7
13	Solder coverage and leaching	7
15	Oversize due to excessive solder din buildun	/ 8



### **Foreword**

This specification was prepared under the cognizance of the P-2.1 Subcommittee on Ceramic Dielectric Capacitors of the Electronic Industries Alliance's sector Electronic Components, Assemblies, Equipment & Supplies Association (EIA/ECA).



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